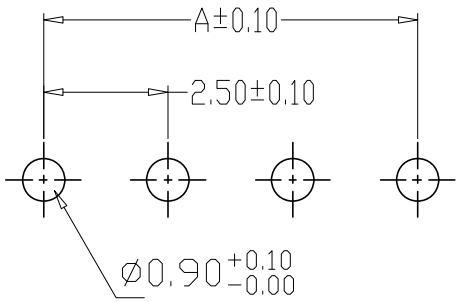
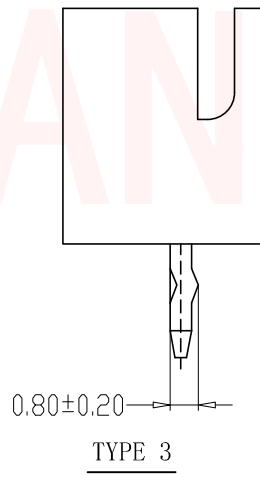
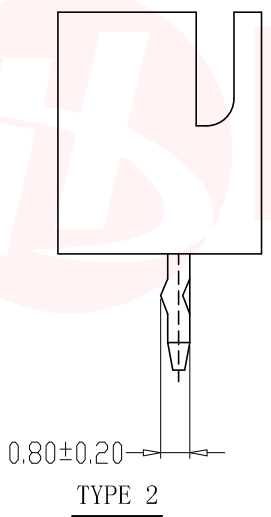
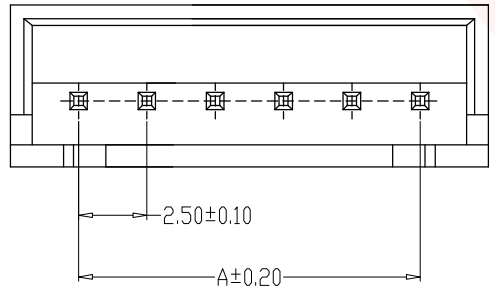
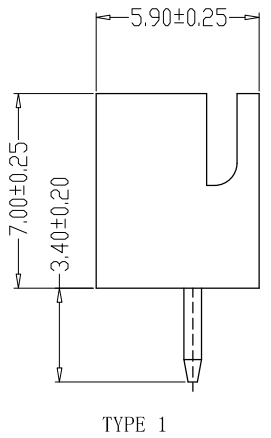
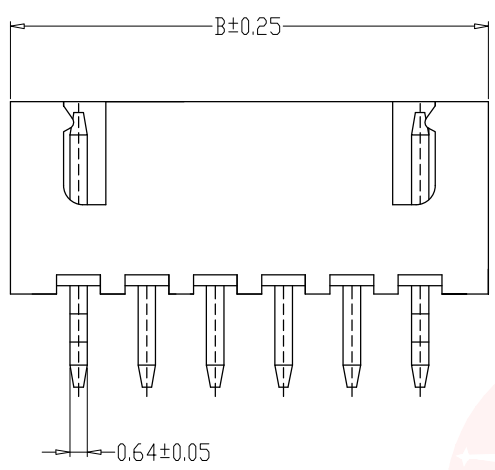




REV.	ECN NO OR DESCRIPTION	REVISED	DATE



**PCB LAYOUT**

**SPECIFICATIONS**

- 1、Current Rating: 3A AC, DC
- 2、Voltage Rating: 250V AC, DC
- 3、Temperatuer Range: -25°C~+85°C
- 4、Contact Resistance: 20mΩ Max
- 5、Insulation Resistance: 1000MΩ Min
- 6、Withstanding Voltang: 1000V AC/minute
- 7、Material: Wafer Nylon66, UL94V-0  
PIN Brass Tin-plated

**TABLE:**

CSG PART NO.	Dimension mm		
	PIN	A	B
WAFER-XH254Z-2A	2P	2.50	7.50
WAFER-XH254Z-3A	3P	5.00	10.00
WAFER-XH254Z-4A	4P	7.50	12.50
WAFER-XH254Z-5A	5P	10.00	15.00
WAFER-XH254Z-6A	6P	12.50	17.50
WAFER-XH254Z-7A	7P	15.00	20.00
WAFER-XH254Z-8A	8P	17.50	22.50
WAFER-XH254Z-9A	9P	20.00	25.00
WAFER-XH254Z-10A	10P	22.50	27.50
WAFER-XH254Z-11A	11P	25.00	30.00
WAFER-XH254Z-12A	12P	27.50	32.50
WAFER-XH254Z-20A	20P	47.50	52.50

序号	名称	材料	电镀 (锡): 整个表面镀底镍 30U"MIN 再镀锡80U" MIN
1	端子/Contact	黄铜	
2	基座/Wafer	LCP/PA66 (UL94V-0)	白色
UNLESS OTHERWISE SPECIFIED TOLERANCES		<b>东莞市汉博电子科技有限公司</b> DONGGUAN HANBO TECHNOLOGY CO., LTD	
DECIMALS: ANGLES:		TITLE: WAFER HA 2.54MM 直针 DIP TYPE	
X :±0.20	X :±2°	DWN	xiong PART NO. WAFER-XH254Z-NA
X.X :±0.10	X.X :±1°	CHKD	lee SCALE:1:1 UNIT: mm
X.XX :±0.05		APVD	wang SIZE: A4 SHEET:10F 1 REV: A4
CUSTOMER COPY			